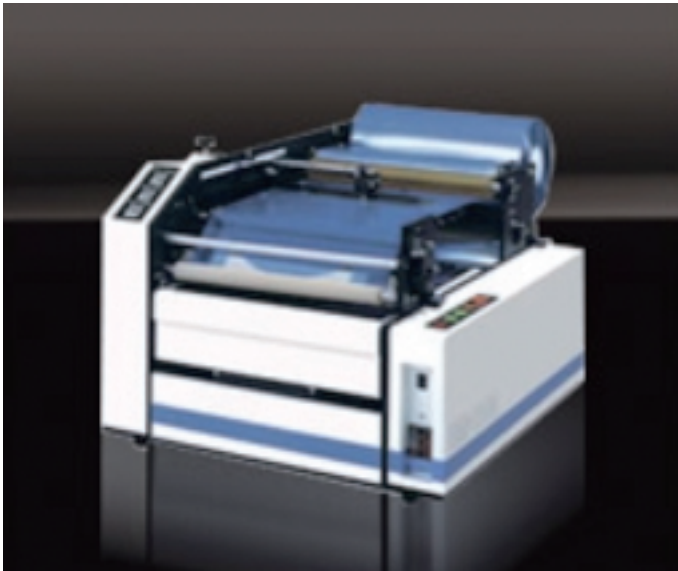


300mm Semi-Automatic Wafer Mounter

RAD-2500m/12



Outline

-Semi-automatic wafer mounter that mounts wafer onto the pre-cut dicing tape once the operator supplies the wafer and ring frame by hand.

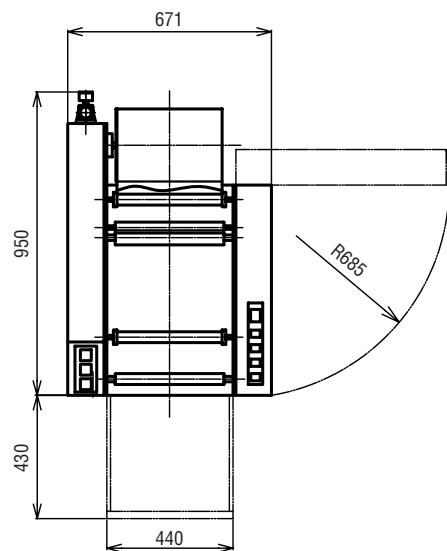
Options

- Static Eliminator
- Top Cover
- Wafer Positioning Pins

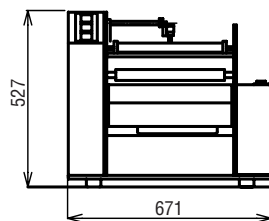
Suitable Tapes

- Pre-cut dicing tape : Adwill D series, G series
- Dicing die bonding tape : Adwill LE Tape

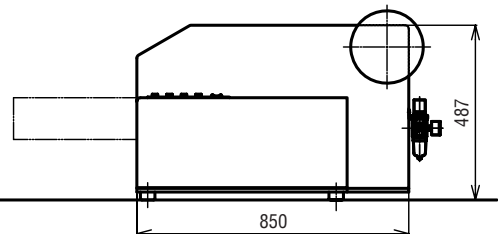
External View



Top View



Front View



Right Side View

Unit:mm

Facility

Power Supply	Voltage	: AC100V (±10%)
	Frequency	: 50/60Hz
	Phase	: single phase
Air Supply	Power consumption	: 0.2KVA
	Air pressure	: 0.5-0.8MPa
	Air consumption	: <150L/min (ANR)

Applicable Wafer Size

300mm
Additional compatibility with various wafer sizes and shapes are available as an option. Please feel free to inquire.

Size

Width : 671mm
Depth : 950mm
(with table fully advanced : Max. 1,380mm)
Height : 527mm

Weight

110kg

Processing Capacity

22sec/wafer (excludes setting time)



LINTEC Corporation *Linking your dreams*

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